



Advance Product Change Notification

201509005A

Issue Date: 04-Jan-2016

Dear

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QUALITY

Management Summary

Assembly site transfer for the 40pin DIP packages of the 8 Bit Microcontroller Product Line from assembly site APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to Amkor Philippines.

Change Category

<input type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Assembly Site Transfer for MCU 40pin DIP Packages (APB Thailand to Amkor Philippines)

Details of this Planned Change

Transfer remaining production of 40pin DIP packages from APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to subcontractor Amkor Philippines. NXP will transfer all remaining production of 40pin DIP packages from in-house assembly APB (Bangkok) to the subcontractor Amkor Philippines.

There will be no changes to the test location. Wafer testing will be performed at APK and final test will be performed at APB.

Package assembly will be transferred from APB to Amkor with the following BOM changes:

1. Die-attach will be changed from Henkel EP121-7NT to Henkel 8361J, which is standard die-attach material at Amkor Philippines.
2. Wire size will change from 23um to 25um.
3. Mold compound will change from EME-6210SR-L to Sumitomo G600, which is standard material at Amkor Philippines.
4. Tube will change from NXP DIP40 tube to Amkor Philippines DIP40 tube.

There will be no changes to silicon wafer thickness, DIP40 leadframe or package outline dimensions.

Why do we Plan this Change

The 40pin DIP packages have been identified as End Of Life (EOL) products.

In order to support current production, NXP has decided to transfer the DIP assembly to NXP's subcontractor Amkor to have sufficient load to maintain these DIP assembly lines.

Identification of Affected Products

Top side marking

Only line 3, second letter, on assembly centre code will be changed from 'n' to 'u'

n - ABP Assembly

u - Amkor Assembly

(Old Marking-TnGYWW, New Marking-TuGYWW)

Product Availability

Sample Information

Samples are available from 01-Mar-2016

Production

Planned first shipment 01-Jun-2016

Impact

no impact to the product's functionality anticipated.

No impact on function, quality, reliability and manufacturability is anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Timing and Logistics

The Self Qualification Report will be ready on 01-Apr-2016.

The Final PCN is planned to be issued on: 01-Apr-2016.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 03-Feb-2016.

For information on shipping and logistics related issues please contact BL Operations Manager

Swaminathan Ramesh at swaminathan.ramesh@nxp.com

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Senior Quality Engineer

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Changed Orderable Part#

P80C51FA-4N,112

P80C32X2FN,112

P87C51RC2FN,112

P87C52SBPN,112

P87C51FB-4N,112

P87C54SBPN,112

P87C51SBPN,112

P87C52X2BN,112

P87C51FA-4N,112

P87C52X2FN,112

P87C51X2BN,112

P87C51RB2BN,112